



## Material Content Data Sheet



<b>Sales Product Name</b>				BSC047N08NS3 G		<b>Issued</b>		28. November 2014	
<b>MA#</b>				MA000445920					
<b>Package</b>				PG-TDSON-8-1		<b>Weight*</b>		122.21 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	4.423	3.62	3.62	36194	36194	
leadframe	non noble metal	iron	7439-89-6	0.038	0.03		309		
	inorganic material	phosphorus	7723-14-0	0.011	0.01		93		
	non noble metal	copper	7440-50-8	37.762	30.89	30.93	309000	309402	
wire	non noble metal	copper	7440-50-8	0.065	0.05	0.05	533	533	
encapsulation	organic material	carbon black	1333-86-4	0.080	0.07		652		
	plastics	epoxy resin	-	5.660	4.63		46317		
	inorganic material	silicondioxide	60676-86-0	34.121	27.92	32.62	279210	326179	
leadfinish	non noble metal	tin	7440-31-5	1.452	1.19	1.19	11879	11879	
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1354	1354	
solder	noble metal	silver	7440-22-4	0.087	0.07		713		
	non noble metal	tin	7440-31-5	0.070	0.06		570		
	non noble metal	lead	7439-92-1	3.327	2.72	2.85	27224	28507	
CLIP plating	noble metal	silver	7440-22-4	1.289	1.06	1.06	10552	10552	
heatspreader	non noble metal	iron	7439-89-6	0.011	0.01		93		
	inorganic material	phosphorus	7723-14-0	0.003	0.00		28		
	non noble metal	copper	7440-50-8	11.320	9.26	9.27	92631	92752	
heat sink CLIP	non noble metal	iron	7439-89-6	0.022	0.02		183		
	inorganic material	phosphorus	7723-14-0	0.007	0.01		55		
	non noble metal	copper	7440-50-8	22.292	18.24	18.27	182410	182648	
*deviation	< 10%		Sum in total:			100.00		1000000	

### Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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